

# Chip Scale Review

## 2019 Editorial Calendar

**(Editorial close date: 12/1/2018)**

**January • February**

Industry Events

New test methodologies for 5G

RF/OTA

Low-temp direct bond interconnect

Thermal debonding and warpage in FOWLP

W2W/D2W & other bonding advances for 3D ICs

Temporary bonding & the challenges of cleaning post debond

3D IC metrology

Discontinuities drive data integration

Innovative materials & processes

Stretchable interconnects

- **APEX Expo**  
San Diego, CA (Jan 26-31)
- **3D & Systems Summit**  
Dresden, Germany (Jan 28-30)
- **SMTA Pan Pac Microelectronics Symposium**  
Kauai, Hawaii (Feb 11-14)
- **FLEX / MEMS & Sensors Technical Congress**  
Monterey, CA (Feb 18-21)

**Ad Space Close Jan 18 - Ad Materials Close Jan 25**

**(Editorial close date: 1/15/19)**

**March • April**

Industry Events

SiP technology, drivers & market trends

3D system packaging

Thin wafer handling

High yield solutions for FOWLP

Solders in semiconductor device assembly

Hi-reliability standards

MEMS sensors

Innovative microelectronic solutions

OSAT new & emerging package offerings

- **TestConX**  
Mesa, AZ (March 3-6)
- **IMAPS Device Packaging**  
Fountain Hills, AZ (March 4-7)
- **SEMI-THERM**  
San Jose, CA (March 18-22)
- **SEMICON China**  
Shanghai, China (March 20-22)
- **ISS Europe**  
Milan, Italy (March 31-April 2)

**Ad Space Close Mar 13 - Materials Close Mar 22**

**(Editorial close date: 3/8)**

**May • June**

Industry Events

AI in packaging

Heterogeneous integration

Multi-die/ substrate heterogeneous packages

Reliability testing

Automotive

Inspection for advanced packaging processes

RF, Final test

Advances in wafer probe

Smart devices and applications

- **SEMICON SE Asia**  
Kuala Lumpur, Malaysia (May 7-9)
- **ECTC**  
Las Vegas, NV (May 28-31)
- **IEEE/SW Test Workshop (SWTW)**  
San Diego, CA (June 2-5)
- **Sensors Expo**  
San Jose, CA (June 25-27)
- **SEMICON West**  
San Francisco, CA (July 9-11)

**Ad Space Close May 8 - Ad Materials Close May 17**

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Notes: Editorial calendar topics and distribution are subject to change without notice and are contingent on logistics and magazine production.

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